

## N and P-Channel Enhancement Mode Power MOSFET

### Description

The NCE1205 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

### General Features

- N-Channel

$V_{DS} = 12V, I_D = 5A$

$R_{DS(ON)} < 32m\Omega @ V_{GS}=4.5V$

$R_{DS(ON)} < 42m\Omega @ V_{GS}=2.5V$

$R_{DS(ON)} < 80m\Omega @ V_{GS}=1.8V$

- P-Channel

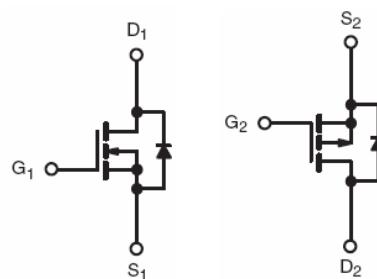
$V_{DS} = -12V, I_D = -5A$

$R_{DS(ON)} < 74m\Omega @ V_{GS}=-4.5V$

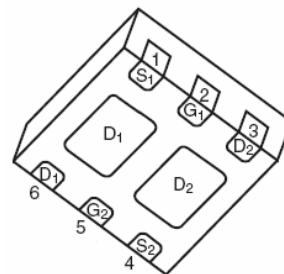
$R_{DS(ON)} < 110m\Omega @ V_{GS}=-2.5V$

$R_{DS(ON)} < 220m\Omega @ V_{GS}=-1.8V$

- Load Switch for Portable Devices



N-channel      P-channel



Pin assignment

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
1205	NCE1205	DFN2X2-6L	-	-	-

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		$V_{DS}$	12	-12	V
Gate-Source Voltage		$V_{GS}$	$\pm 12$	$\pm 12$	V
Continuous Drain Current	$T_A=25^\circ C$	$I_D$	5	-5	A
	$T_A=70^\circ C$		4.5	-3.8	
Pulsed Drain Current <sup>(Note 1)</sup>		$I_{DM}$	20	-15	A
Maximum Power Dissipation	$T_A=25^\circ C$	$P_D$	1.9	1.9	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 To 150	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance,Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	N-Ch	65	°C/W
Thermal Resistance,Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	P-Ch	65	°C/W

N-CH Electrical Characteristics ( $T_A=25^\circ C$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	12	20	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=12V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.4	0.6	1	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=5A$	-	28	32	$m\Omega$
		$V_{GS}=2.5V, I_D=4.6A$	-	36	42	$m\Omega$
		$V_{GS}=1.8V, I_D=4.1A$	-	55	80	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=10V, I_D=5A$	-	20	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	$C_{iss}$	$V_{DS}=6V, V_{GS}=0V, F=1.0MHz$	-	495	-	PF
Output Capacitance	$C_{oss}$		-	155	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	95	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=6V, R_L=1.2\Omega, V_{GS}=10V, R_{GEN}=4.5\Omega$	-	7.0	-	nS
Turn-on Rise Time	$t_r$		-	5.0	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	18	-	nS
Turn-Off Fall Time	$t_f$		-	6	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=6V, I_D=5A, V_{GS}=4.5V$	-	6.6	-	nC
Gate-Source Charge	$Q_{gs}$		-	1	-	nC
Gate-Drain Charge	$Q_{gd}$		-	1.2	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=5A$	-	-	1.2	V

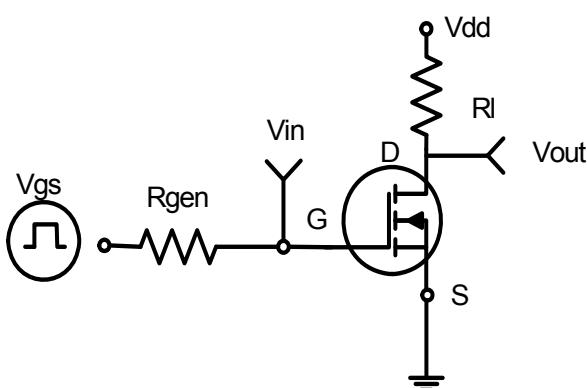
P-CH Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-12	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-12\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.4	-0.7	-1	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-4.5\text{A}$	-	60	74	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-3.2\text{A}$	-	84	110	$\text{m}\Omega$
		$V_{\text{GS}}=-1.8\text{V}, I_{\text{D}}=-1\text{A}$	-	130	220	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-5\text{A}$	-	10	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-6\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	520	-	PF
Output Capacitance	$C_{\text{oss}}$		-	100	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	65	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-6\text{V}, R_{\text{L}}=2.3\Omega$ $V_{\text{GS}}=-10\text{V}, R_{\text{GEN}}=6\Omega$	-	7.5	-	nS
Turn-on Rise Time	$t_{\text{r}}$		-	5.5	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	19	-	nS
Turn-Off Fall Time	$t_{\text{f}}$		-	7	-	nS
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{DS}}=-6\text{V}, I_{\text{D}}=-4.5\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	-	9.2	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	1.6	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	2.2	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=-5\text{A}$	-	-	-1.2	V

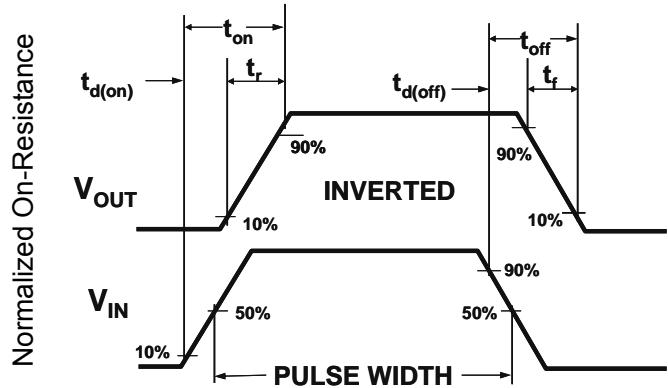
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

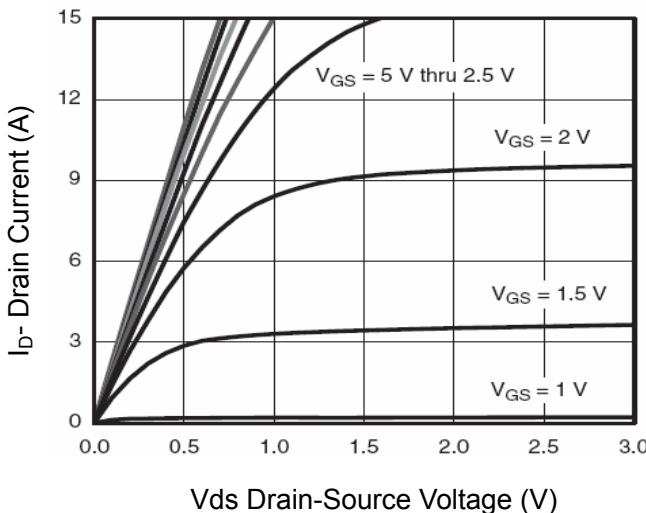
### N- Channel Typical Electrical and Thermal Characteristics (Curves)



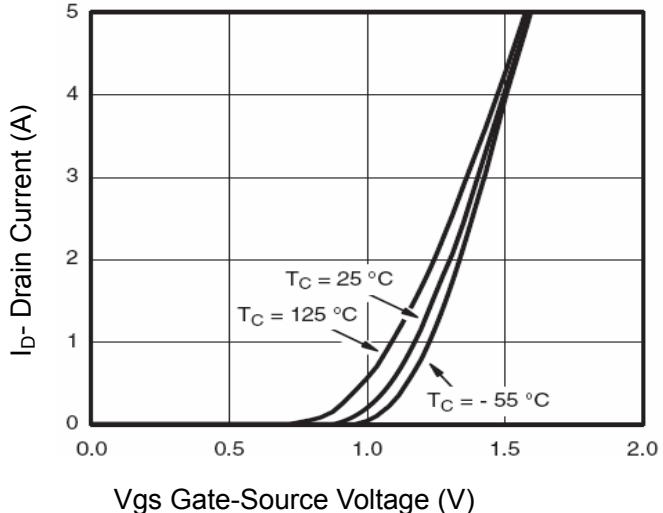
**Figure 1:Switching Test Circuit**



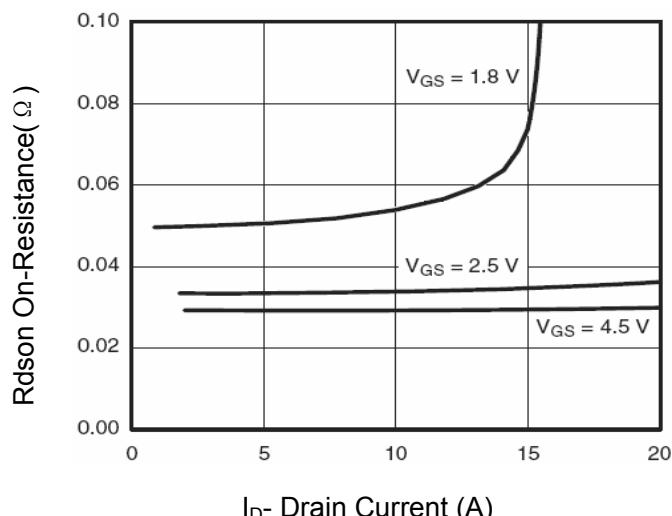
**Figure 2:Switching Waveforms**



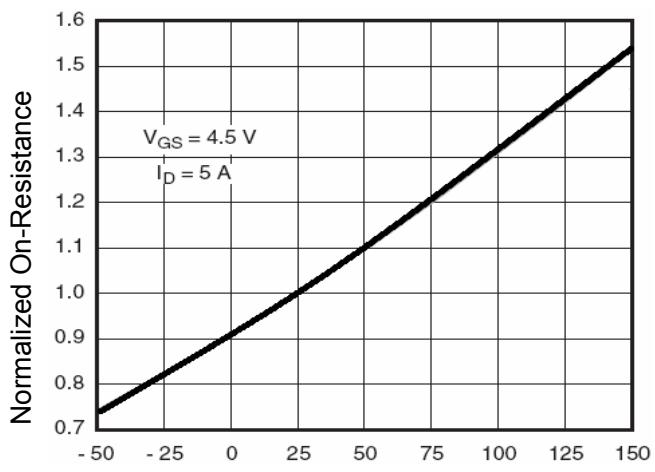
**Figure 3 Output Characteristics**



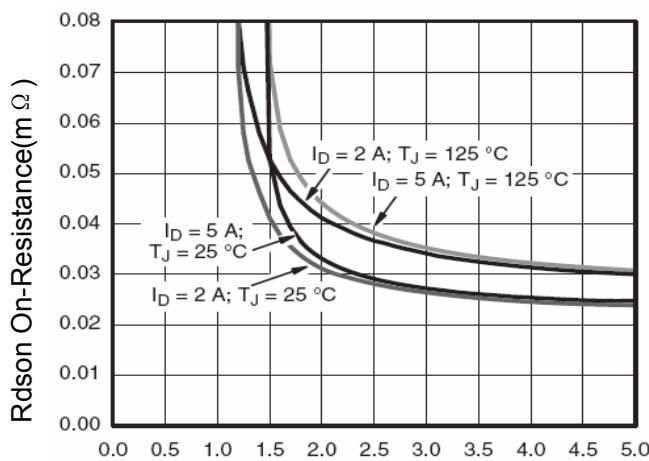
**Figure 4 Transfer Characteristics**



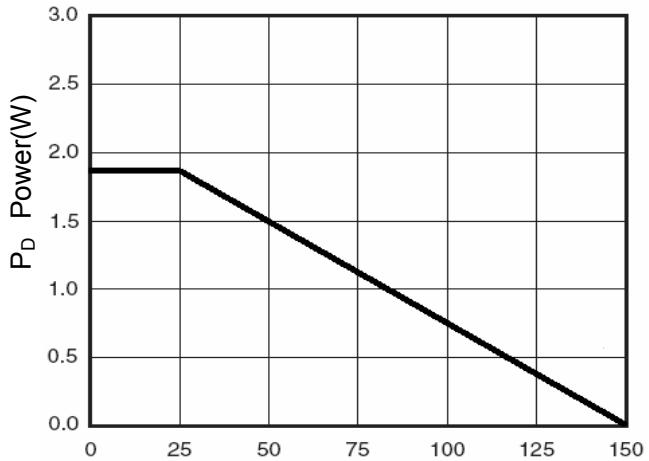
**Figure 5 Drain-Source On-Resistance**



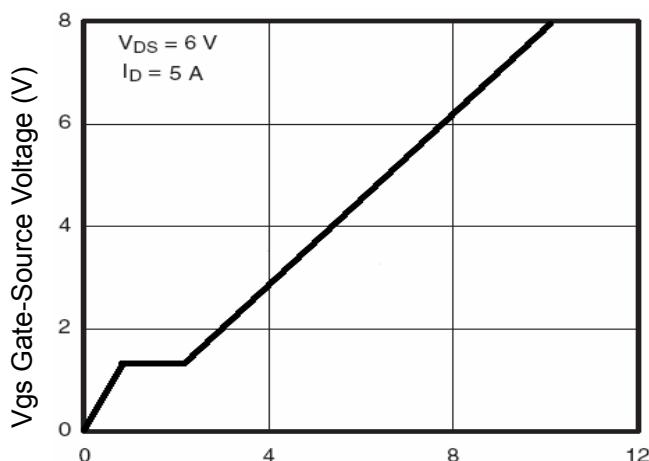
**Figure 6 Drain-Source On-Resistance**



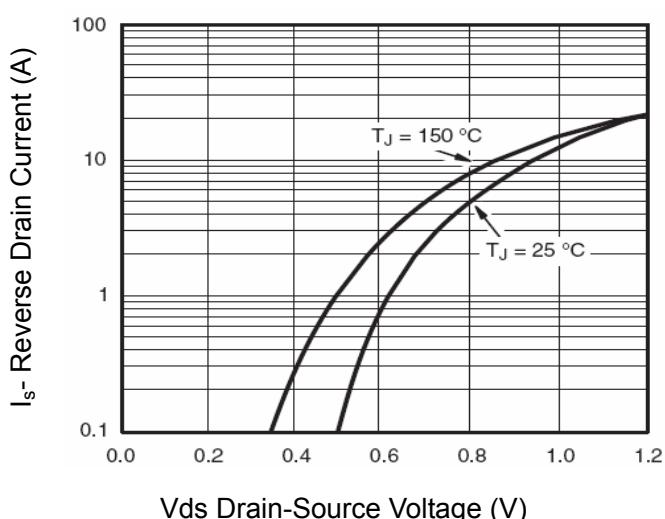
**Figure 7 Rdson vs Vgs**



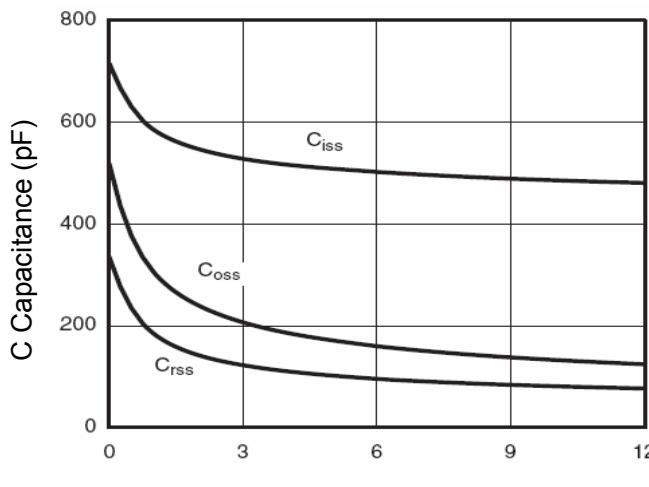
**Figure 8 Power Dissipation**



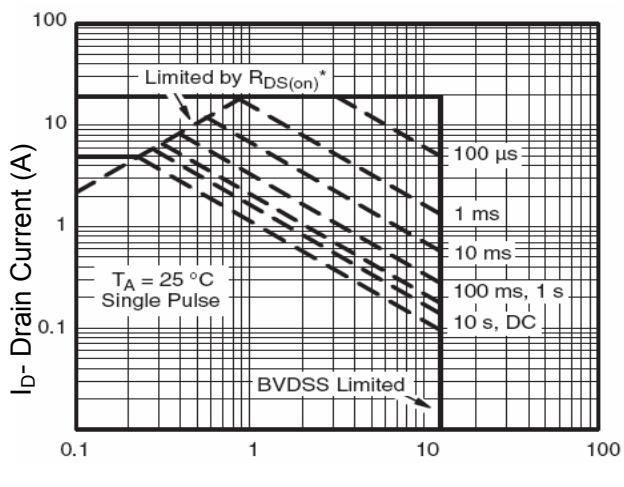
**Figure 9 Gate Charge**



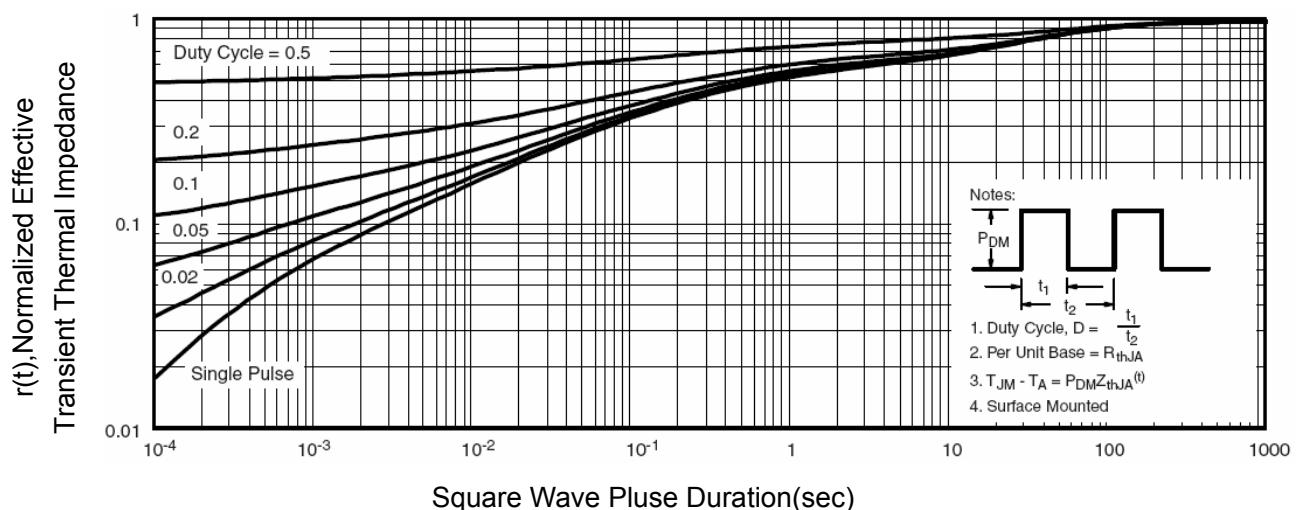
**Figure 10 Source- Drain Diode Forward**



**Figure 11 Capacitance vs Vds**

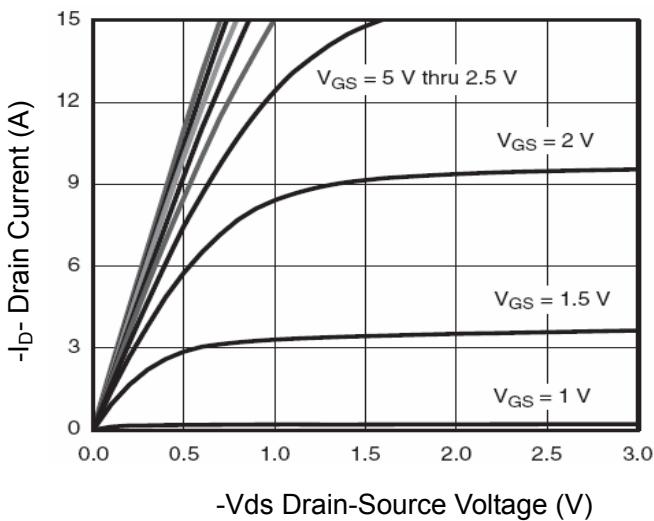


**Figure 12 Safe Operation Area**

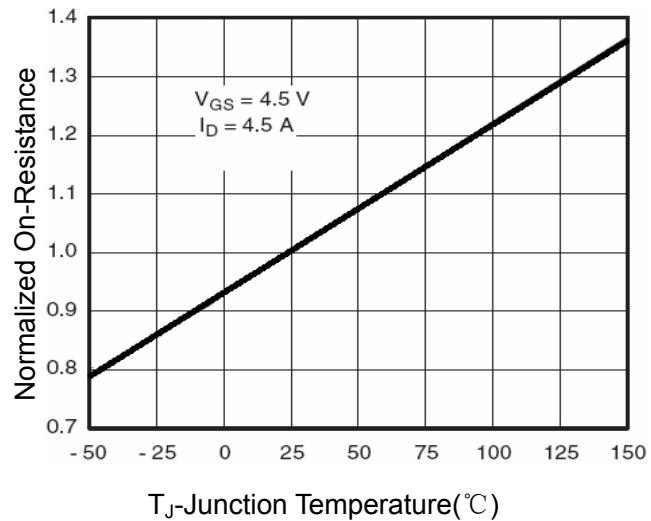


**Figure 13 Normalized Maximum Transient Thermal Impedance**

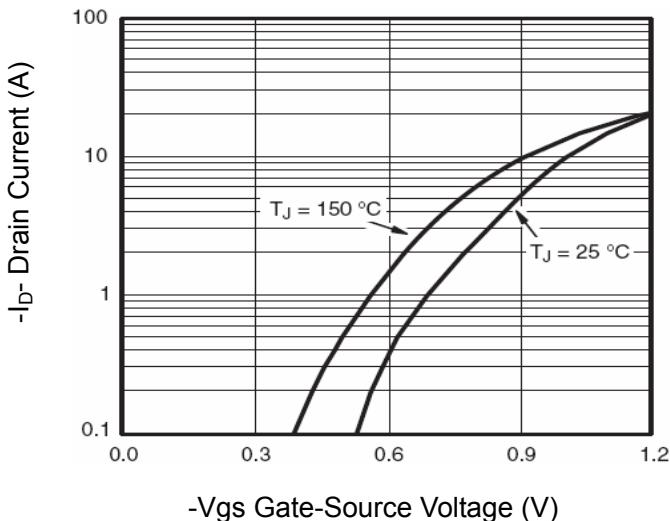
### P- Channel Typical Electrical and Thermal Characteristics (Curves)



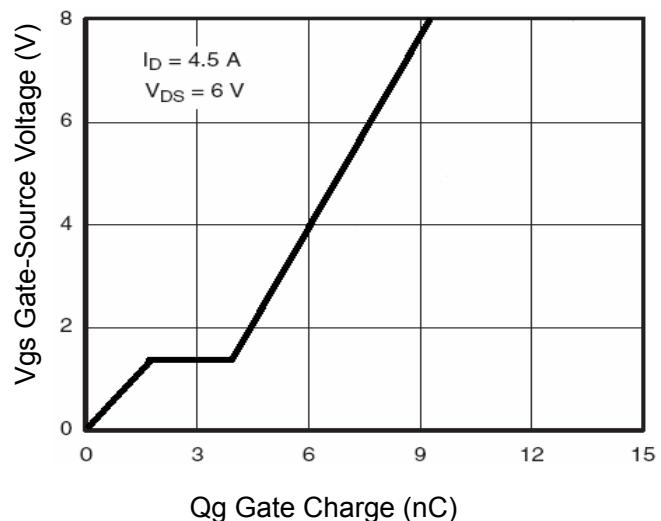
**Figure 1 Output Characteristics**



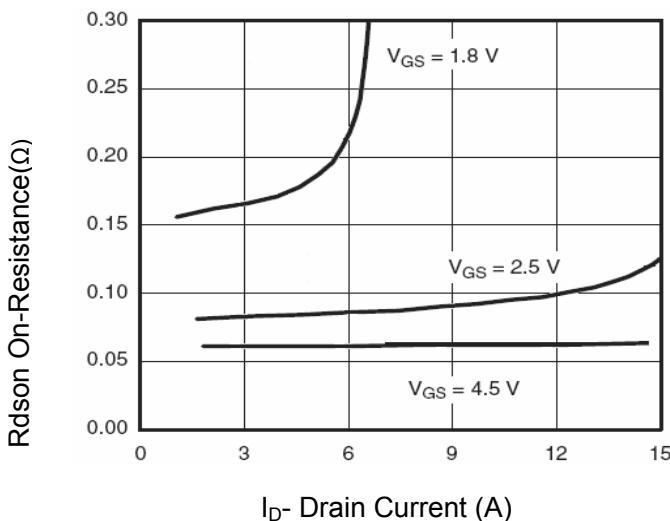
**Figure 4 Rdson-Junction Temperature**



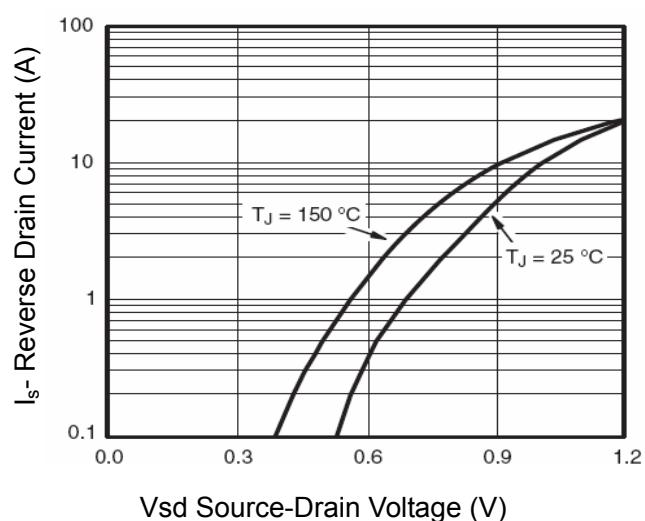
**Figure 2 Transfer Characteristics**



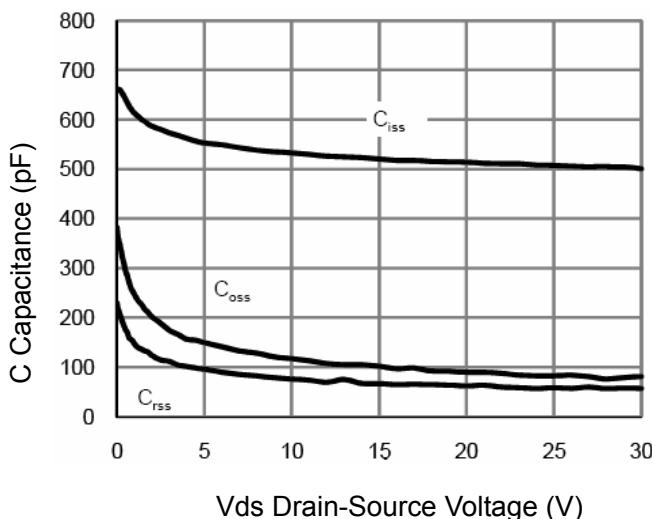
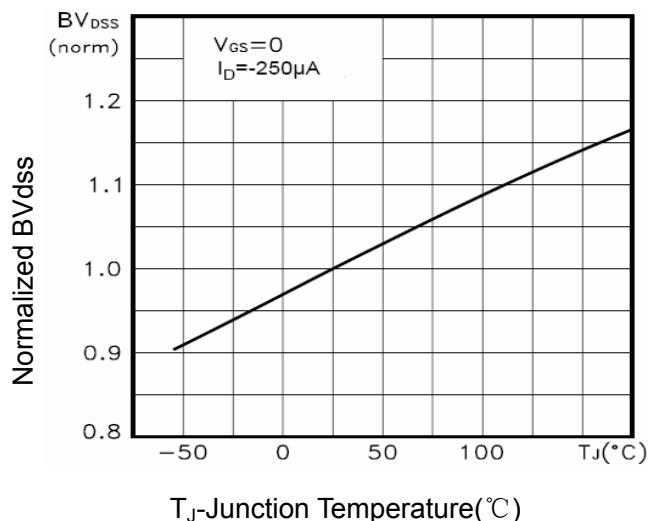
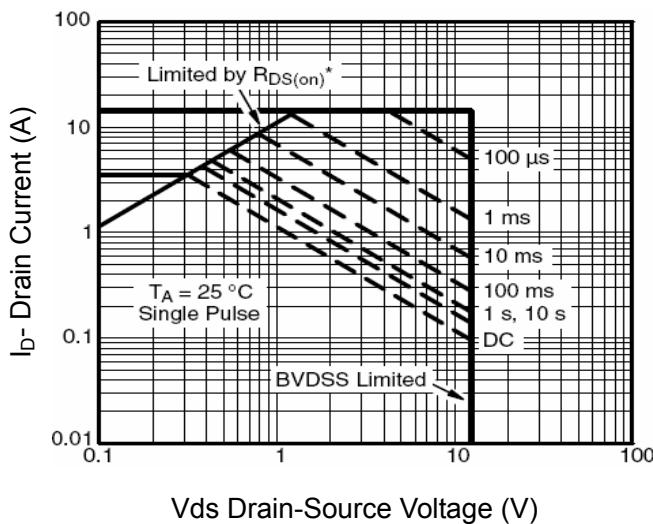
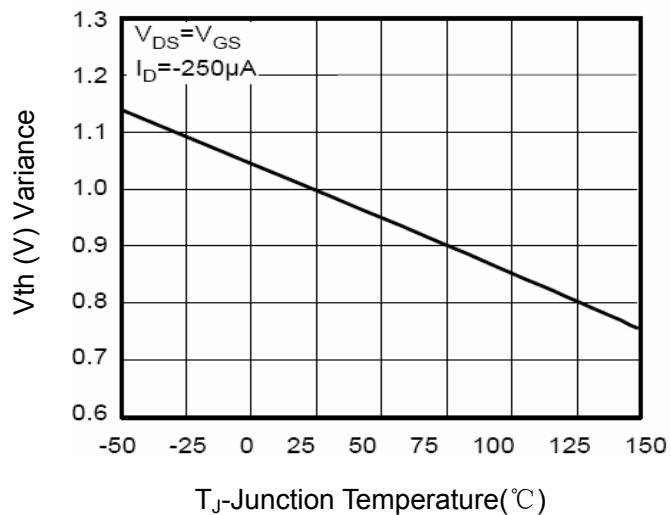
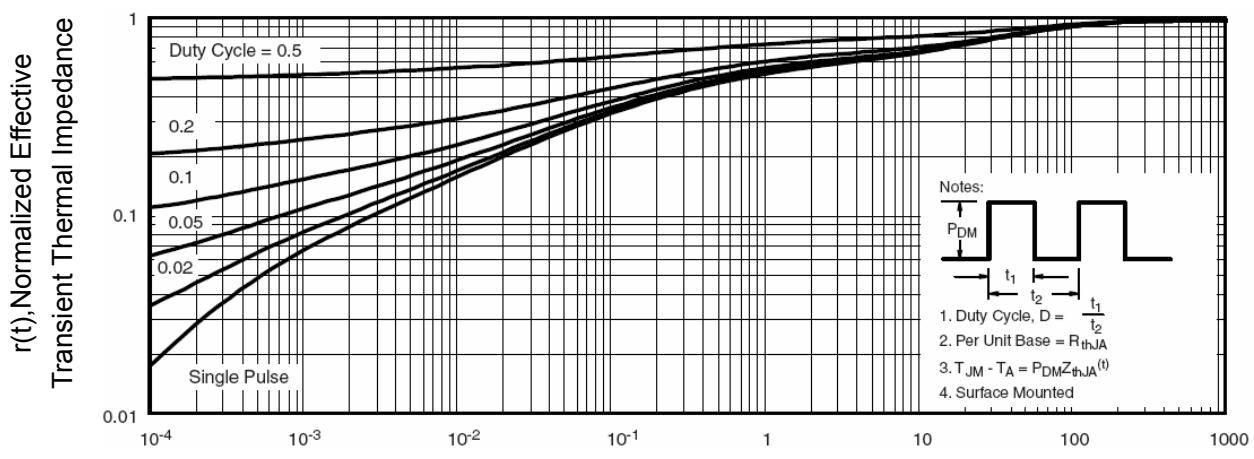
**Figure 5 Gate Charge**

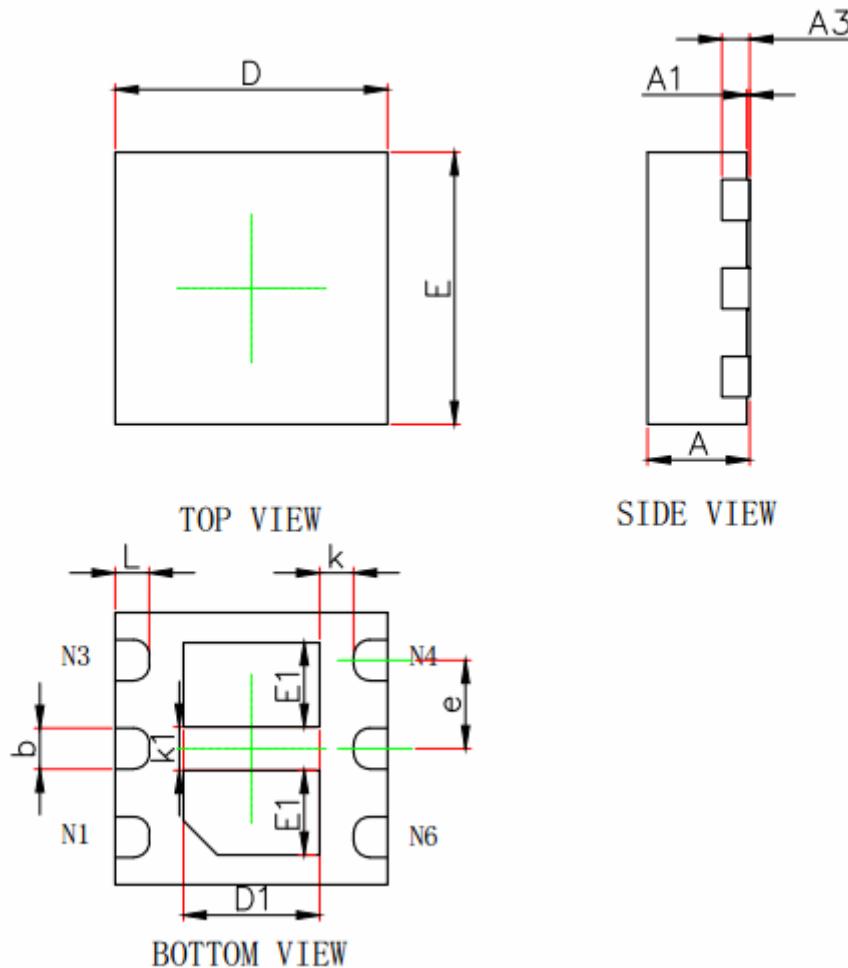


**Figure 3 Rdson- Drain Current**



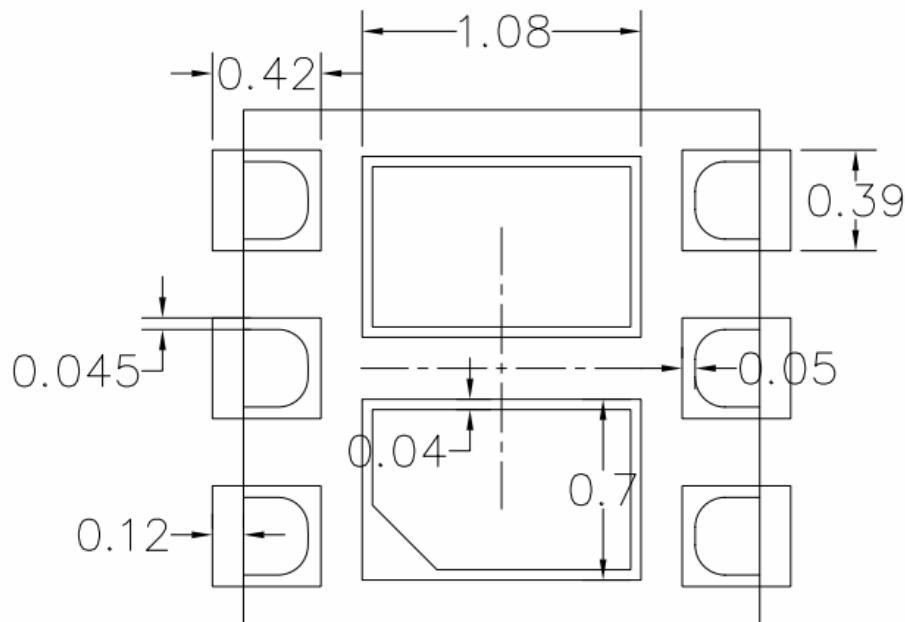
**Figure 6 Source- Drain Diode Forward**


**Figure 7 Capacitance vs Vds**

**Figure 9  $BV_{dss}$  vs Junction Temperature**

**Figure 8 Safe Operation Area**

**Figure 10  $V_{GS(th)}$  vs Junction Temperature**

**Figure 11 Normalized Maximum Transient Thermal Impedance**

**DFN2X2-6L Package Information**


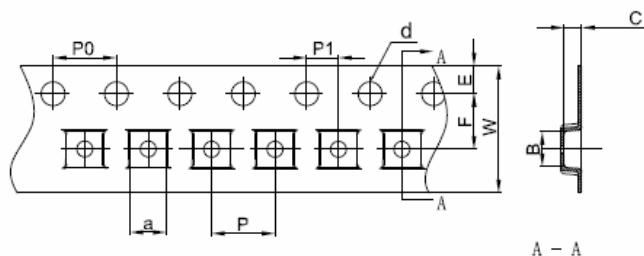
<b>Symbol</b>	<b>Dimensions In Millimeters</b>		<b>Dimensions In Inches</b>	
	<b>MIN.</b>	<b>MAX.</b>	<b>MIN.</b>	<b>MAX.</b>
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.900	2.100	0.075	0.083
E	1.900	2.100	0.075	0.083
D1	0.900	1.100	0.035	0.043
E1	0.520	0.720	0.020	0.028
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
k	0.200MIN.		0.008MIN.	
k1	0.320REF		0.013REF.	
L	0.200	0.300	0.008	0.012

### DFNWB2X2-6L Suggested Pad Layout



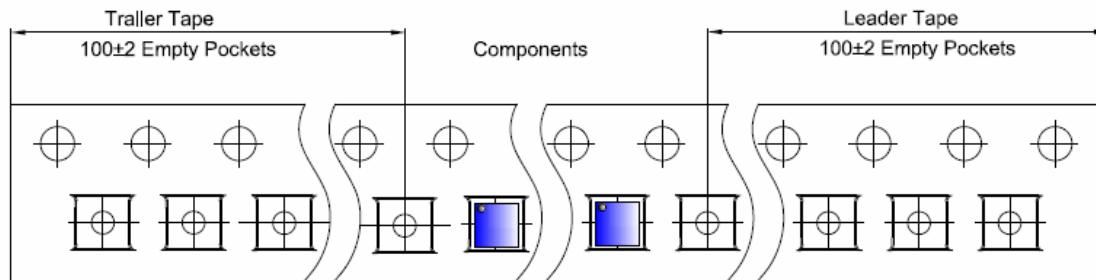
### DFNWB2X2-6L Tape and Reel

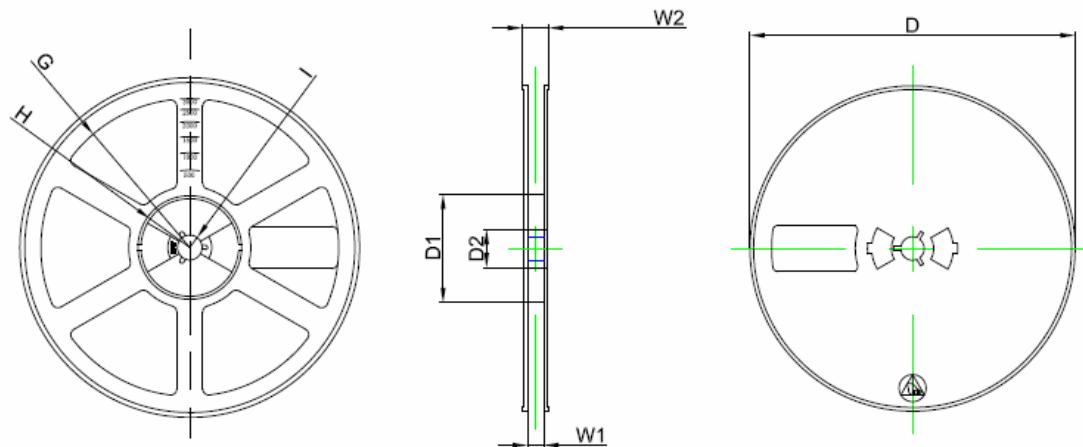
DFNWB2×2-6L Embossed Carrier Tape



Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
DFNWB2×2-6L	2.30	2.30	1.10	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

### DFNWB2×2-6L Tape Leader and Trailer



**DFNWB2×2-6L Reel**


Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
7"Dla	Ø180.00	60.00	13.00	R78.00	R25.60	R6.50	9.50	13.10

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	



## Attention

- Any and all NCE power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your NCE power representative nearest you before using any NCE power products described or contained herein in such applications.
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- This catalog provides information as of Sep.2010. Specifications and information herein are subject to change without notice.